

# Hardware Implementation of HEVC CABAC Binary Arithmetic Encoder

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## Abstract

In this paper, hardware architecture of BAE (binary arithmetic encoder) was proposed for HEVC (high efficiency video coding) CABAC (context-based adaptive binary arithmetic coding) encoder. It can encode each bin in a single cycle. It consists of controller, regular encoding engine, bypass encoding engine, and termination engine. The proposed BAE was designed in Verilog HDL, and it was implemented in 180 nm technology. Its operating speed, gate count, and power consumption are 180 MHz, 3,690 gates, and 2.88 mW, respectively.

Key words: *HEVC, CABAC, binary arithmetic encoder, hardware, implementation*

## I. Introduction

HEVC (high-efficiency video coding) [1]-[7] is the newest video coding standard and the successor to H.264/AVC (advanced video coding). When compared to H.264/AVC, HEVC shows higher compression ratio with more complex hardware implementation.

HEVC uses CABAC (context-based adaptive binary arithmetic coding) for encoding syntax element and generating bitstream. It is an entropy coding with high coding efficiency. As shown in Fig. 1, CABAC encoder consists of four main blocks: binarizer, context modeler, BAE (binary arithmetic encoder), and bitstream generator [5]. First, binarizer converts non-binary-valued syntax elements into binary symbols (called as bins). Second, context modeler calculates and updates the

probability of each bin. Third, BAE converts bins into bits based on the probability from context modeler. Finally, bitstream generator combines output bits of BAE into bitstream.

In this paper, hardware architecture of BAE was proposed for HEVC CABAC encoder. It was designed in Verilog HDL as an independent module that can be integrated into HEVC CABAC encoder. It was simulated, verified, and implemented in 180nm technology.

## II. HEVC CABAC Binary Arithmetic Encoding

HEVC CABAC BAE is an entropy encoding with lossless data compression. It overcomes some limitations of Huffman coding such as non-integer length and probability distribution change.

It uses a certain interval, and probability of each bin narrows down the interval. Therefore the outcome gets fewer bits than the original bins. BAE has two variables to represent the interval: *ivlLow* and *ivlRange*. There are three encoding processes in BAE: regular encoding, bypass encoding, and termination. They are described in the Figs. 2-4.

Regular encoding is applied to the symbols with changing distribution. In the regular encoding process, BAE gets context model from context

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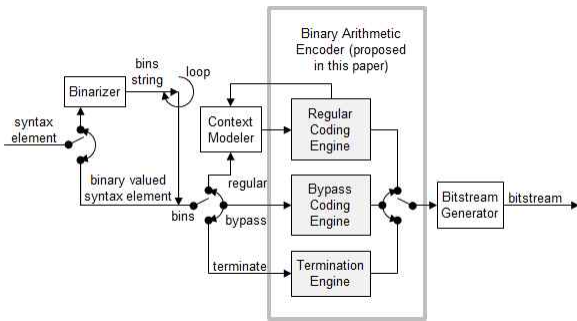


Fig. 1. Block diagram of HEVC CABAC encoder. (Modified from [5])

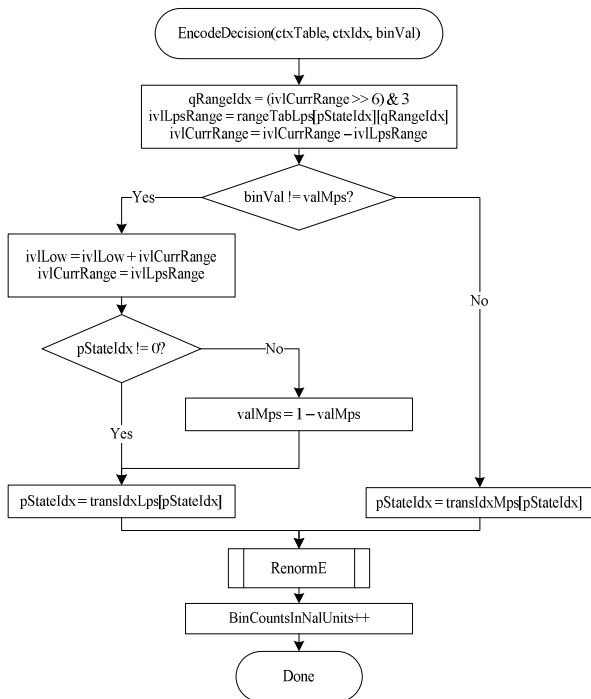


Fig. 2. Regular encoding process. (Modified from [1],[8])

modeler after context model is updated. Bypass encoding is applied to the symbols with equal distribution, i.e. its appearance frequency is unchanged. Termination is applied to the symbols indicating the end of encoding. Unlike regular encoding, bypass encoding and termination do not need context modeling.

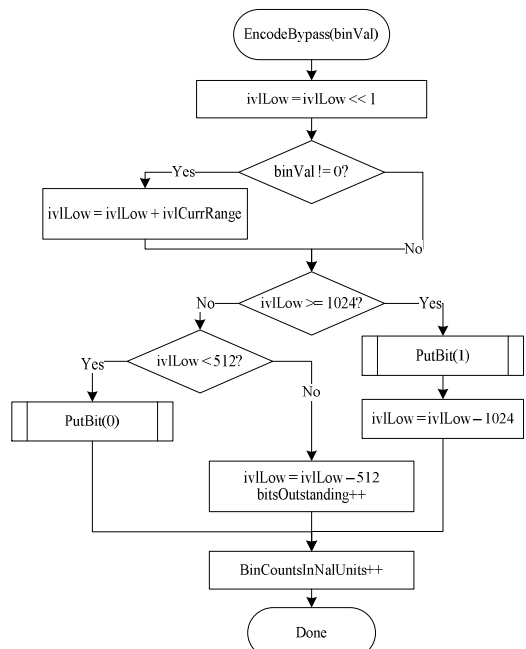


Fig. 3. Bypass encoding process. (Modified from [1],[8])

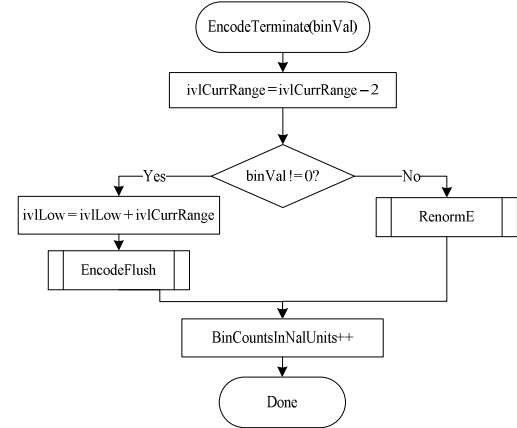


Fig. 4. Termination process. (Modified from [1],[8])

### III. Hardware Architecture

#### 1. Top Architecture

The proposed BAE consists of four modules such as controller module, regular encoding engine, bypass encoding engine, and termination engine, as shown in Fig. 5.

The controller is connected to binarizer and

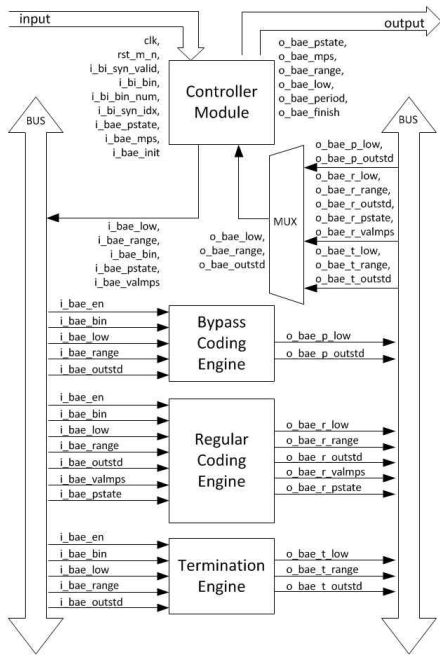


Fig. 5. Architecture of the proposed BAE.

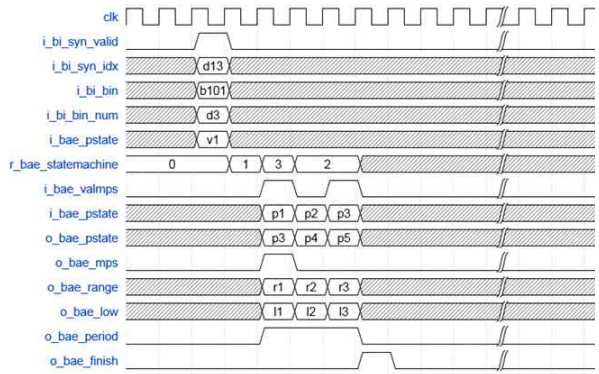


Fig. 6. Timing diagram of the proposed BAE.

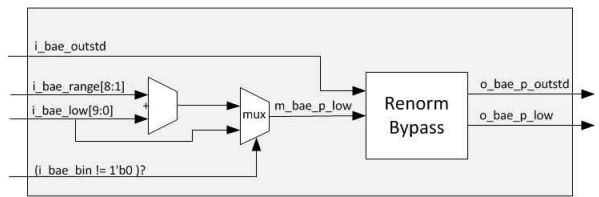


Fig. 7. Bypass encoding engine.

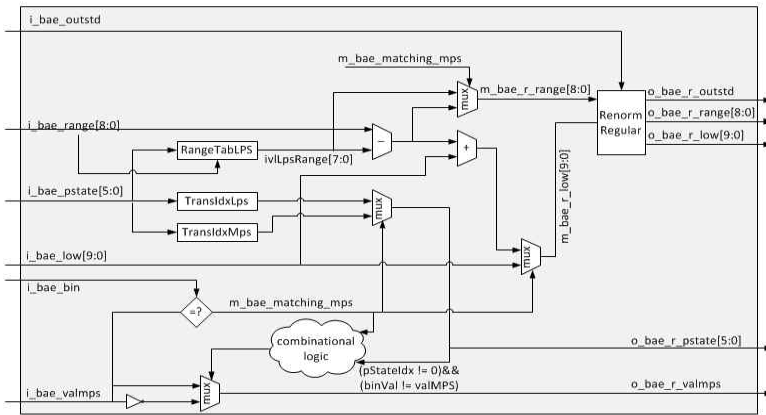


Fig. 8. Regular encoding engine.

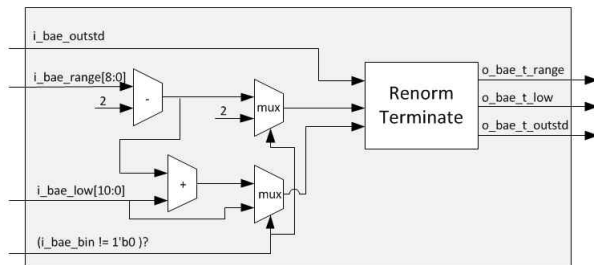


Fig. 9. Termination engine.

context modeler to get bin string and context modelling information of each bin. It determines the encoding mode of each bin and assign it to the corresponding encoding engine. It assigns *ivlLow* and *ivlRange* to regular encoding engine, bypass encoding engine, and termination engine. Updated output variables are sent to output port via multiplexer and they are stored in the buffer to encode next bin. Fig. 6 shows the timing chart of BAE.

## 2. Bypass Encoding Engine

The bypass coding engine gets four input variables (*ivlLow*, *ivlRange*, *binVal*, *outstanding count*) from the controller. *ivlLow* is updated in the renormalization phase for bypass bin. The bypass encoding engine is designed as shown in Fig. 7.

## 3. Regular Encoding Engine

The regular encoding engine gets six input variables (*ivlLow*, *ivlRange*, *binVal*, *outstanding count*, *pstate*, *valMps*) from the controller.

*ivlLpsRange* is derived from the lookup table of *RangeTabLPS*. *TransIdxMps* and *TransIdxLps* are defined in the lookup tables of [1]. Update condition of *pstate* and *valmps* is as follows.

```

if (binVal == valMps)
    pStateIdx = transIdxMps(pStateIdx);
else {
    if(pStateIdx == 0)
        valMps = 1 - valMps;
    pStateIdx = transIdxLps(pStateIdx);
}

```

*ivlRange* and *ivlLow* are updated in the renormalization phase for regular bin. The regular encoding engine is designed as shown in Fig. 8.

## 4. Termination Engine

The termination engine gets four input variables (*ivlLow*, *ivlRange*, *binVal*, *outstanding count*) from the controller. *ivlRange* and *ivlLow* are updated in the renormalization phase. The termination engine is

designed as shown in Fig. 9.

## 5. Renormalization

Renormalization in the software [2] can take some cycles. In hardware implementation, this can be reorganized to operate in one cycle by using the number of zero leading detection (ZLD) in *ivlRange* variable. Implementation of ZLD is described in [5].

## IV. Experiments and Results

The proposed BAE was designed in Verilog HDL. 4 standard test sequences (class A, B, C, and D) with 3 encoder configurations (low delay, random access, and all intra) were generated from HEVC HM-11 reference software [2], as shown in Table 1. These 12 test vectors were used in the front-end simulation with Verilog HDL, and the designed BAE was passed in all tests.

The designed BAE was implemented in 180 nm technology. CAD tool was supported by IC Design Education Center (IDEC). As shown in Table 2, the operating speed, gate count, and power consumption of the back-end design are 180 MHz, 3,960 gates, and 2.88 mW, respectively. Its critical path delay is 5.2 ns. It can encode one bin in a single cycle.

## V. Conclusions

Table 1. Test sequences.

| Sequence   | Class A  | Class B       | Class C     | Class D     |
|------------|--|---------------|-------------|-------------|
| Size       | 2560x<br>1600  | 1920x<br>1080 | 832x<br>480 | 416x<br>240 |
| Frame Rate | 30   | 24            | 50          | 50          |
| Frames     | 10   | 10            | 10          | 10          |
| Bit Depth  | 8  | 8             | 8           | 8           |
| Encoder    | 3 Configurations (low delay, random access, and all intra) |               |             |             |

Table 2. Synthesis Results.

|                     |             |
|---------------------|-------------|
| Technology          | 180 nm      |
| Operating Frequency | 180 MHz     |
| Gate Counts         | 3,960 gates |
| Critical Path Delay | 5.2 ns      |
| Dynamic Power       | 2.88 mW     |
| Leakage Power       | 1.55 uW     |

In this paper, a binary arithmetic encoder for HEVC CABAC encoder was proposed. It was designed in Verilog HDL with 4 modules to cover 3 processing modes. It was implemented in 180 nm technology. It can encode one bin per cycle. Its operating speed, gate count, and power consumption are 180 MHz, 3,960 gates, and 2.88 mW, respectively.

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